

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint (34) inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

"PLANISHING APPARATUS AND METHOD"

the specification of which

(check one) X is attached hereto.

_____ was filed on _____ as
Application Serial No. _____
and was amended on _____ (if
applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Serial No. 60/083,398

Filing Date 4/29/98

Status Pending

I hereby appoint the following attorneys to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith: William H. Meise, Registration No. 27,574, Geoffrey H. Krauss, Registration No. 27,343, Stephen A. Young, Registration No. 25,048, John J. Morrissey, Registration No. 26,208; Gay Chin, Registration No.

18,875; and Patrick M. Hogan, Registration No. 29,543.

Direct all correspondence and telephone calls to: William H. Meise,
Patent Operation, Lockheed Martin Corporation, Room 314B, Bldg. 28,
P. O. Box 8048, Philadelphia, PA 19101, (610) 354-6426.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: Richard Allen Venable

Inventor's signature: Richard Allen Venable Date: 7-15-98

Residence: 395 Walker Rd., Grant, Marshall County, AL

Citizenship: USA

Post Office Address: 395 Walker Rd., Grant, AL 35747

Full name of second inventor: Kenneth Glenn Ezell

Inventor's signature: Kenneth Glenn Ezell Date: 7/15/98

Residence: 167 Winter Ridge Drive, Madison, Madison County, AL

Citizenship: USA

Post Office Address: 167 Winter Ridge Drive, Madison, AL 35757

Full name of third inventor: David Eugene Hartley

Inventor's signature: David E. Hartley Date: 7/27/98

Residence: 1011 Oakland Dr., Pearl River, St. Tammany Parish, LA

Citizenship: USA

Post Office Address: 1011 Oakland Dr., Pearl River, LA 70452

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Richard Allen Venable et al.
Title: *Planishing Apparatus and Method*
Filed: Herewith


TRUE COPY STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

The undersigned, a registered patent attorney, hereby verifies that the accompanying specification (with claims), drawings, and Declaration showing signatures, are a true copy of the parent or prior complete application, serial number 09/134,634, filed 8/14/98.

Respectfully submitted,

BY: 
William H. Meise
Registration No. 27,574

November 23, 1999
Enclosures

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